

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
HIDEKI HARIYA	03/30/2017
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SHIN-ETSU HANDOTAI CO., LTD.
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<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	15534904
<b>CORRESPONDENCE DATA</b>	
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<b>ATTORNEY DOCKET NUMBER:</b>	027667.00020
<b>NAME OF SUBMITTER:</b>	ERIC WOLKWITZ
<b>SIGNATURE:</b>	/eric wolkwitz/
<b>DATE SIGNED:</b>	06/12/2017
<b>Total Attachments: 1</b>	
source=027667-00020_Assignment-as-filed_06-12-2017#page1.tif	

Docket No. 027667.00020

**U.S. ASSIGNMENT**

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter ASSIGNOR) by

[Insert  
ASSIGNEE's  
Name(s)  
Address(es)]

SHIN-ETSU HANDOTAI CO., LTD.2-1, Ohtemachi 2-chome, Chiyoda-kuTokyo, Japan 100-0004

(hereinafter ASSIGNEE), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest, including the right to sue for past infringement, if any, and all rights pursuant to 35 U.S.C. §154, to the invention entitled

[Title of  
Invention]

METHOD OF MANUFACTURING EPITAXIAL WAFER

[\*If the assignment  
is being filed  
after the filing of the  
application, this  
section must be  
completed]

for which application for Letters Patent of the United States was executed on even date herewith unless otherwise indicated below:

filed on June 9, 2017, Serial No. 15/534,904

(Arent Fox LLP is hereby authorized to insert the series code, serial number and/or filing date hereon, when known)

and all Letters Patent of the United States to be obtained therefor on said application or any continuation, division, renewal, substitute, reissue or reexamination thereof, and any other application claiming priority thereto, for the full term or terms for which the same may be granted.

The ASSIGNOR agrees to execute all papers necessary in connection with application and any continuing, divisional, reissue or reexamination applications thereof and also to execute separate assignments in connection with such applications as the ASSIGNEE may deem necessary or expedient.

The ASSIGNOR agrees to execute all papers necessary in connection with any interference, litigation, or other legal proceeding which may be declared concerning this application or any continuation, division, reissue or reexamination thereof or Letters Patent or reissue patent issued thereon and to cooperate with the ASSIGNEE in every way possible in obtaining and producing evidence and proceeding with such interference, litigation, or other legal proceeding.

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

[Signature(s)  
of Assignor(s)]



(SIGNATURE)

Hideki HARIYA

(TYPE NAME)

March 30 2017

(DATE)